

### **General Description**

The MAX3679 is a low-jitter precision clock generator with the integration of three LVPECL and one LVCMOS outputs optimized for Ethernet applications. The device integrates a crystal oscillator and a phase-locked loop (PLL) clock multiplier to generate high-frequency clock outputs for Ethernet applications.

Maxim's proprietary PLL design features ultra-low jitter (0.36ps<sub>RMS</sub>) and excellent power-supply noise rejection, minimizing design risk for network equipment.

### **Applications**

Ethernet Networking Equipment

### Pin Configuration appears at end of data sheet.

### **Features**

- Crystal Oscillator Interface: 25MHz
- ♦ CMOS Input: 25MHz
- Output Frequencies for Ethernet 62.5MHz, 125MHz, 156.25MHz, 312.5MHz
- Low Jitter
   0.14ps<sub>RMS</sub> (1.875MHz to 20MHz)
   0.36ps<sub>RMS</sub> (12kHz to 20MHz)
- Excellent Power-Supply Noise Rejection
- No External Loop Filter Capacitor Required

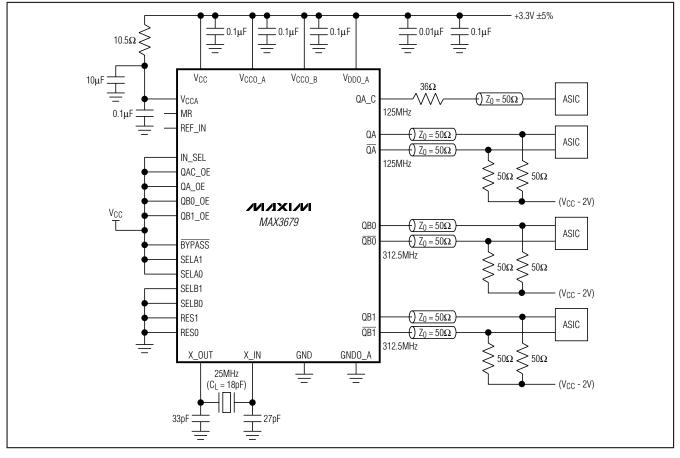
### Ordering Information

PART	TEMP RANGE	PIN-PACKAGE			
MAX3679CTJ+	0°C to +70°C	32 TQFN-EP*			

+Denotes a lead-free/RoHS-compliant package.

\*EP = Exposed pad.

## **Typical Application Circuit**



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# **MAX3679**

### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage Range V <sub>CC</sub> , V <sub>CCA</sub> ,	
VDDO_A, VCCO_A, VCCO_B	0.3V to +4.0V
Voltage Range at REF_IN, IN_SEL,	
SELA[1:0], SELB[1:0], RES[1:0],	
QAC_OE, QA_OE, QB0_OE, QB1_OE,	
MR, BYPASS	0.3V to (V <sub>CC</sub> + 0.3V)
Voltage Range at X_IN Pin	0.3V to +1.2V

Voltage Range at GNDO_A	0.3V to +0.3V
Voltage Range at X_OUT	0.3V to (V <sub>CC</sub> - 0.6V)
Current into QA_C	±50mA
Current into QA, QA, QB0, QB0, QB1, QB	156mA
Continuous Power Dissipation ( $T_A = +70^{\circ}$ C	C)

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

(V<sub>CC</sub> = +3.0V to +3.6V,  $T_A = 0^{\circ}$ C to +70°C, unless otherwise noted. Typical values are at V<sub>CC</sub> = +3.3V,  $T_A = +25^{\circ}$ C, unless otherwise noted.) (Notes 1, 2, and 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Power-Supply Current	Icc	(Note 4)		77	100	mA
CONTROL INPUT CHARACTER (SELA[1:0], SELB[1:0], IN_SEL,		_OE, QB1_OE, QB0_OE, MR, BYPASS Pins	)			
Input Capacitance	CIN			2		pF
Input Pulldown Resistor	RPULLDOWN	Pin MR		75		kΩ
Input Logic Bias Resistor	RBIAS	Pins SELA[1:0], SELB[1:0], QB0_OE		50		kΩ
Input Pullup Resistor	Rpullup	Pins QAC_OE, QA_OE, QB1_OE, IN_SEL, BYPASS	75			kΩ
LVPECL OUTPUT SPECIFICAT	ONS (QA, QA	, QB0, QB0, QB1, QB1 Pins)				
Output High Voltage	VOH		V <sub>CC</sub> - 1.13	V <sub>CC</sub> - 0.98	V <sub>CC</sub> - 0.83	V
Output Low Voltage	V <sub>OL</sub>		V <sub>CC</sub> - 1.85	V <sub>CC</sub> - 1.7	V <sub>CC</sub> - 1.55	V
Peak-to-Peak Output-Voltage Swing (Single-Ended)		(Note 2)	0.6	0.72	0.9	VP-P
Clock Output Rise/Fall Time		20% to 80% (Note 2)	200	350	600	ps
Output Duty-Cycle Distortion		PLL enabled	48	50	52	%
Output Duty-Cycle Distortion		PLL bypassed (Note 5)	40	50	60	/0
LVCMOS/LVTTL INPUT SPECIF (SELA[1:0], SELB[1:0], IN_SEL,		OE, QB1_OE, QB0_OE, MR, BYPASS Pins	)			
Input-Voltage High	VIH		2.0			V
Input-Voltage Low	VIL				0.8	V
Input High Current	IIН	V <sub>IN</sub> = V <sub>CC</sub>			80	μA
Input Low Current	ΙL	$V_{IN} = 0V$	-80			μA



### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = +3.0V \text{ to } +3.6V, T_A = 0^{\circ}C \text{ to } +70^{\circ}C, \text{ unless otherwise noted.} Typical values are at V_{CC} = +3.3V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$  (Notes 1, 2, and 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
<b>REF_IN SPECIFICATIONS (Input</b>	DC- or AC-	Coupled)	•			1
		PLL enabled		25		
Reference Clock Frequency		PLL bypassed			320	MHz
Input-Voltage High	VIH		2.0			V
Input-Voltage Low	VIL				0.8	V
Input High Current	Ιн	$V_{IN} = V_{CC}$			240	μA
Input Low Current	١ <sub>١L</sub>	$V_{IN} = 0V$	-240			μA
Reference Clock Duty Cycle		PLL enabled	30		70	%
Input Capacitance				2.5		pF
QA_C SPECIFICATIONS			•			
Output High Voltage	VOH	QA_C sourcing 12mA	2.6			V
Output Low Voltage	Vol	QA_C sinking 12mA			0.4	V
Output Rise/Fall Time		(Notes 3 and 6)	250	500	1000	ps
Output Duty-Cycle Distortion		PLL enabled	42	50	58	- %
		PLL bypassed (Note 5)	40		60	
Output Impedance				14		Ω
CLOCK OUTPUT AC SPECIFICA	TIONS					
VCO Frequency Range				625		MHz
Dandam littar (Nata 7)		12kHz to 20MHz		0.36	1.0	
Random Jitter (Note 7)	RJ <sub>RMS</sub>	1.875MHz to 20MHz		0.14		psrms
Deterministic Jitter Due to Supply Noise (Notes 7, 8, 9)		LVPECL output		5.0		psp-p
Spurs Induced by Power-Supply		LVPECL output         -59           LVCMOS output         -47		-59		
Noise (Notes 7, 9, 10)				-47		- dBc
Nonharmonic and Subharmonic Spurs				-70		dBc
		Between QB0 and QB1		15		
Output Skew		Between QA and QB0 or QB1, PECL outputs		20		ps

## **ELECTRICAL CHARACTERISTICS (continued)**

(V<sub>CC</sub> = +3.0V to +3.6V,  $T_A$  = 0°C to +70°C, unless otherwise noted. Typical values are at V<sub>CC</sub> = +3.3V,  $T_A$  = +25°C unless otherwise noted.) (Notes 1, 2, and 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Clock Output SSB Phase Noise at 125MHz (Note 11)		f = 1kHz		-124		
		f = 10kHz		-125		
		f = 100kHz		-130		dBc/Hz
		f = 1MHz		-145		
		f > 10MHz		-153		

**Note 1:** A series resistor of up to  $10.5\Omega$  is allowed between V<sub>CC</sub> and V<sub>CCA</sub> for filtering supply noise when system power-supply tolerance is V<sub>CC</sub> =  $3.3V \pm 5\%$ . See Figure 2.

- Note 2: Guaranteed up to 320MHz for LVPECL output.
- **Note 3:** Guaranteed up to 160MHz for LVCMOS output.
- Note 4: All outputs enabled and unloaded. IN\_SEL set high.
- Note 5: Measured with crystal or AC-coupled, 50% duty-cycle signal on REF\_IN.
- **Note 6:** Measured using setup shown in Figure 1 with  $V_{CC} = 3.3V \pm 5\%$ .
- Note 7: Measured with crystal source.

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- **Note 8:** Total TIE including random and deterministic jitter. Measured with Agilent DSO81304A 40GS/s real-time oscilloscope using 2M sample record length.
- Note 9: Measured with 40mV<sub>P-P</sub>, 100kHz sinusoidal signal on the supply.
- Note 10: Measured at 156.25MHz output.
- Note 11: Measured with 25MHz crystal or 25MHz reference clock at LVCMOS input with a slew rate of 0.5V/ns or greater.

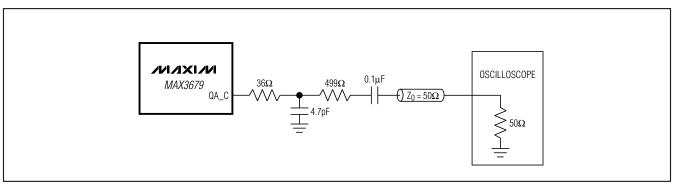


Figure 1. LVCMOS Output Measurement Setup

### **Typical Operating Characteristics**

(Typical values are at  $V_{CC}$  = +3.3V,  $T_A$  = +25°C, crystal frequency = 25MHz.)

SUPPLY CURRENT **DIFFERENTIAL OUTPUT WAVEFORM OUTPUT WAVEFORM AT 125MHz** AT 156.25MHz (LVPECL OUTPUT) vs. TEMPERATURE (LVCMOS OUTPUT) AX3679 toc03 250 MEASURED USING 50Ω OSCILLOSCOPE INPUT 225 THROUGH NETWORK SHOWN IN FIGURE 1 200 ALL OUTPUTS ACTIVE AND TERMINATED AMPLITUDE (200mv/div) AMPLITUDE (50mV/div) 175 150 125 100 ALL OUTPUTS ACTIVE AND UNTERMINATED 75 50 25 0 0 10 20 30 40 50 60 70 80 1ns/div 1ns/div AMBIENT TEMPERATURE (°C) **PHASE NOISE AT 312.5MHz PHASE NOISE AT 125MHz CLOCK FREQUENCY CLOCK FREQUENCY** -80 -80 -90 -90 NOISE POWER DENSITY (dBc/Hz) NOISE POWER DENSITY (dBc/Hz) -100 -100 -110 -110 -120 -120 -130 -130 -140 -140 -150 -150 -160 -160 10 1000 10,000 100,000 0.1 10 1000 10,000 100,000 0.1 100 100 OFFSET FREQUENCY (kHz) OFFSET FREQUENCY (kHz) JITTER HISTOGRAM (312.5MHz OUTPUT, **NOISE SPUR AMPLITUDE** 40mV<sub>P-P</sub> SUPPLY NOISE AT 100kHz) vs. NOISE FREQUENCY 0  $f_{C} = 156.25 MHz$ -10 NOISE AMPLITUDE = 40mVP-P -20 SPUR AMPLITUDE (dBc) 4  $DJ = 5.0ps_{P-P}$ -30 -40 -50 -60 -70 -80 -90 10 100 1000 10,000 5ps/div NOISE FREQUENCY (kHz)

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SUPPLY CURRENT (mA)

### **Pin Description**

PIN	NAME	FUNCTION
1	Vcco_b	Power Supply for QB0 and QB1 Clock Outputs. Connect to +3.3V.
2, 19, 24	GND	Supply Ground
3	QB0_OE	LVCMOS/LVTTL Input. Enables/disables QB0 clock output. Connect pin high to enable LVPECL clock output QB0. Connect low to set QB0 to a logic 0. Has internal $50k\Omega$ input impedance.
4, 5	SELB1, SELB0	LVCMOS/LVTTL Input. Controls NB divider setting. Has $50k\Omega$ input impedance. See Table 2 for more information.
6	QAC_OE	LVCMOS/LVTTL Input. Enables/disables QA_C clock output. Connect pin high to enable QA_C. Connect low to set QA_C to a high-impedance state. Has internal 75k $\Omega$ pullup to V <sub>CC</sub> .
7	MR	LVCMOS/LVTTL Input. Master reset input. Pulse high for > 1 $\mu$ s to reset all dividers. Has internal 75k $\Omega$ pulldown to GND. Not required for normal operation.
8	GNDO_A	Ground for QA_C Output. Connect to supply ground.
9	QA_C	LVCMOS Clock Output
10	Vddo_a	Power Supply for QA_C Clock Output. Connect to +3.3V.
11	Vcco_a	Power Supply for QA Clock Output. Connect to +3.3V.
12	QA	Noninverting Clock Output, LVPECL
13	QA	Inverting Clock Output, LVPECL
14	BYPASS	LVCMOS/LVTTL Input (Active Low). Connect low to bypass the internal PLL. Connect high for normal operation. When in bypass mode the output dividers are set to divide by 1. Has internal $75$ k $\Omega$ pullup to V <sub>CC</sub> .
15	RES1	Not Internally Connected. Connect to GND, V <sub>CC</sub> , or leave open for normal operation.
16	RES0	Reserved for Test. Connect to GND for normal operation.
17	V <sub>CCA</sub>	Analog Power Supply for the VCO. Connect to +3.3V. For additional power-supply noise filtering, this pin can connect to $V_{CC}$ through 10.5 $\Omega$ as shown in Figure 2 (requires $V_{CC}$ = +3.3V ±5%).
18	Vcc	Core Power Supply. Connect to +3.3V.
20	QA_OE	LVCMOS/LVTTL Input. Enables/disables the QA clock output. Connect this pin high to enable the LVPECL clock output QA. Connect low to set QA to a logic 0. Has internal 75k $\Omega$ pullup to V <sub>CC</sub> .
21, 22	SELA0, SELA1	LVCMOS/LVTTL Input. Controls NA divider setting. See Table 2 for more information. Has $50k\Omega$ input impedance.
23	QB1_OE	LVCMOS/LVTTL Input. Enables/disables QB1 clock output. Connect pin high to enable LVPECL clock output QB1. Connect low to set QB1 to a logic 0. Has internal $50k\Omega$ input impedance.
25	X_OUT	Crystal Oscillator Output
26	X_IN	Crystal Oscillator Input
27	REF_IN	LVCMOS Reference Clock Input. Self-biased to allow AC- or DC-coupling.
28	IN_SEL	LVCMOS/LVTTL Input. Connect high or leave open to use a crystal. Connect low to use REF_IN. Has internal $75k\Omega$ pullup to V <sub>CC</sub> .
29	QB1	LVPECL, Inverting Clock Output
30	QB1	LVPECL, Noninverting Clock Output
31	QBO	LVPECL, Inverting Clock Output
32	QB0	LVPECL, Noninverting Clock Output
_	EP	Exposed Pad. Connect to supply ground for proper electrical and thermal performance.

M/XI/M

### **Detailed Description**

The MAX3679 is a low-jitter clock generator designed to operate at Ethernet frequencies. It consists of an on-chip crystal oscillator, PLL, programmable dividers, LVCMOS output buffer, and LVPECL output buffers. Using a lowfrequency clock (crystal or CMOS input) as a reference, the internal PLL generates a high-frequency output clock with excellent jitter performance.

### **Crystal Oscillator**

An integrated oscillator provides the low-frequency reference clock for the PLL. This oscillator requires an external crystal connected between X\_IN and X\_OUT. Crystal frequency is 25MHz.

### **REF\_IN Buffer**

An LVCMOS-compatible clock source can be connected to REF\_IN to serve as the reference clock.

The LVCMOS REF\_IN buffer is internally biased to allow AC- or DC-coupling. It is designed to operate up to 320MHz.

### PLL

The PLL takes the signal from the crystal oscillator or reference clock input and synthesizes a low-jitter, high-frequency clock. The PLL contains a phase-frequency detector (PFD), a lowpass filter, and a 625MHz voltage-controlled oscillator (VCO). The VCO output is connected to the PFD input through a feedback divider. See Table 3 for divider values. The PFD compares the reference frequency to the divided-down VCO output (fvCO/25) and generates a control signal that keeps the VCO locked to the reference clock. The high-frequency VCO output clock is sent to the output dividers. To minimize noise- induced jitter, the VCO supply (V<sub>CCA</sub>) is isolated from the core logic and output buffer supplies.

### **Output Dividers**

The output divider is programmable to allow a range of output frequencies. See Table 2 for the divider input settings. The output dividers are automatically set to divide by 1 when the MAX3679 is in bypass mode (BYPASS = 0).

### **LVPECL Drivers**

The high-frequency outputs—QA, QB0, and QB1—are differential PECL buffers designed to drive transmission lines terminated with 50 $\Omega$  to V<sub>CC</sub> - 2.0V. The maximum operating frequency is specified up to 320MHz. Each output can be individually disabled, if not used. The outputs go to a logic 0 when disabled.

### **LVCMOS Driver**

QA\_C, the LVCMOS output, is designed to drive a single-ended high-impedance load. The maximum operating frequency is specified up to 160MHz. This output can be disabled by the QAC\_OE pin if not used and goes to a high impedance when disabled.

### **Reset Logic/POR**

During power-on, the power-on reset (POR) signal is generated to synchronize all dividers. An external master reset (MR) signal is not required.

## Applications Information

### **Power-Supply Filtering**

The MAX3679 is a mixed analog/digital IC. The PLL contains analog circuitry susceptible to random noise. In addition to excellent on-chip power-supply noise rejection, the MAX3679 provides a separate power-supply pin, V<sub>CCA</sub>, for the VCO circuitry. Figure 2 illustrates the recommended power-supply filter network for V<sub>CCA</sub>. The purpose of this design technique is to ensure clean input power supply to the VCO circuitry and to improve the overall immunity to power-supply noise. This network requires that the power supply is +3.3V ±5%. Decoupling capacitors should be used on all other supply pins for best performance.

### **Output Divider Configuration**

Table 2 shows the input settings required to set the output dividers. Leakage in the OPEN case must be less than 1 $\mu$ A. Note that when the MAX3679 is in bypass mode (BYPASS set low), the output dividers are automatically set to divide by 1.

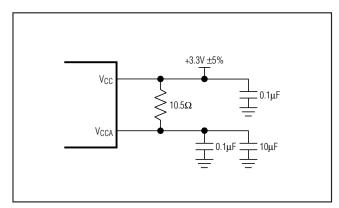


Figure 2. Analog Supply Filtering

XO OR CMOS INPUT FREQUENCY (MHz)	FEEDBACK DIVIDER, M	VCO FREQUENCY (MHz)	OUTPUT DIVIDER, NA AND NB	OUTPUT FREQUENCY (MHz)	APPLICATIONS						
	25 25 625	÷2	312.5								
25		25	25 25	625	625	625	625	25 625	÷4	156.25	Ethernet
20 20		025	025		÷5	125	Ethernet				
			÷10	62.5							

### Table 1. Output Frequency Determination Chart

### Table 2. Output Divider Configuration Chart

INF	NA/NB DIVIDER	
SELA1/SELB1	SELA0/SELB0	
0	0	÷2*
1	0	÷4
1	1	÷5
0	OPEN	÷10

\*Maximum guaranteed output frequency is 160MHz for CMOS and 320MHz for LVPECL output.

### **Table 3. Crystal Selection Parameters**

PARAMETER	SYMBOL	MIN	ТҮР	МАХ	UNITS
Crystal Oscillation Frequency	fosc		25		MHz
Shunt Capacitance	Co		2.0	7.0	pF
Load Capacitance	CL		18		pF
Equivalent Series Resistance (ESR)	Rs			50	Ω
Maximum Crystal				300	μW

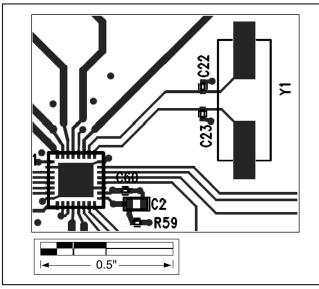


Figure 3. Crystal Layout

### **Crystal Selection**

The crystal oscillator is designed to drive a fundamental mode, AT-cut crystal resonator. See Table 3 for recommended crystal specifications. See Figure 4 for external capacitance connection.

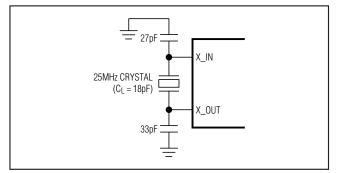


Figure 4. Crystal, Capacitors Connection

### Crystal Input Layout and Frequency Stability

The crystal, trace, and two external capacitors should be placed on the board as close as possible to the MAX3679's X\_IN and X\_OUT pins to reduce crosstalk of active signals into the oscillator.

The layout shown in Figure 3 gives approximately 3pF of trace plus footprint capacitors per side of the crystal (Y1). The dielectric material is FR-4 and dielectric thickness of the reference board is 15 mils. Using a 25MHz crystal and the capacitor values of C22 = 27pF and C23 = 33pF, the measured output frequency accuracy is -14ppm at +25°C ambient temperature.



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### Interfacing with LVPECL Outputs

The equivalent LVPECL output circuit is given in Figure 8. These outputs are designed to drive a pair of  $50\Omega$  transmission lines terminated with  $50\Omega$  to V<sub>TT</sub> = V<sub>CC</sub> - 2V. If a separate termination voltage (V<sub>TT</sub>) is not available, other

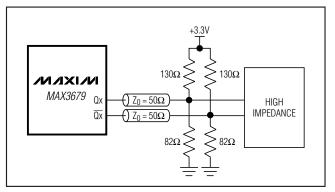


Figure 5. Thevenin Equivalent of Standard PECL Termination

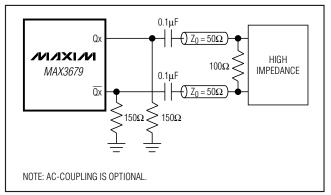


Figure 6. AC-Coupled PECL Termination

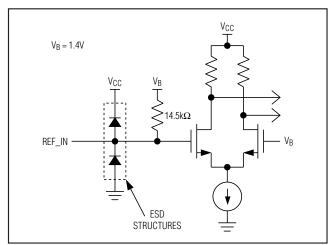


Figure 7. Simplified REF\_IN Pin Circuit Schematic

termination methods can be used such as shown in Figures 5 and 6. Unused outputs should be disabled and can be left open. For more information on LVPECL terminations and how to interface with other logic families, refer to Application Note 291: *HFAN-01.0: Introduction to LVDS, PECL, and CML.* 

### Interface Models

Figures 7, 8, and 9 show examples of interface models.

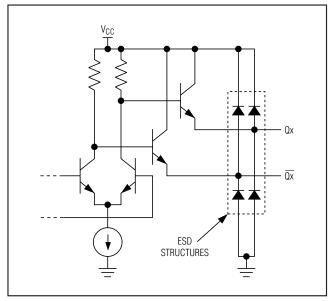


Figure 8. Simplified LVPECL Output Circuit Schematic

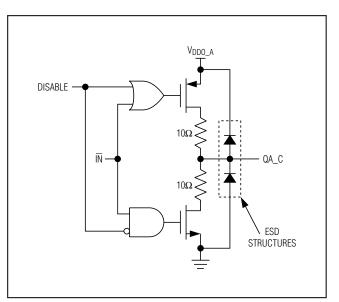


Figure 9. Simplified LVCMOS Output Circuit Schematic

# **WAX3679**

### **Layout Considerations**

The inputs and outputs are critical paths for the MAX3679, and care should be taken to minimize discontinuities on these transmission line. Here are some suggestions for maximizing the MAX3679's performance:

- An uninterrupted ground plane should be positioned beneath the clock I/Os.
- Ground pin vias should be placed close to the IC and the input/output interfaces to allow a return current path to the MAX3679 and the receive devices.
- Supply decoupling capacitors should be placed close to the MAX3679 supply pins.
- Maintain  $100\Omega$  differential (or  $50\Omega$  single-ended) transmission line impedance out of the MAX3679.
- Use good high-frequency layout techniques and a multilayer board with an uninterrupted ground plane to minimize EMI and crosstalk.

Refer to the MAX3679 Evaluation Kit for more information.

### **Exposed-Pad Package**

The exposed pad on the 32-pin TQFN package provides a very low inductance path for return current traveling to the PCB ground plane. The pad is also electrical ground on the MAX3679 and must be soldered to the circuit board ground for proper electrical performance.

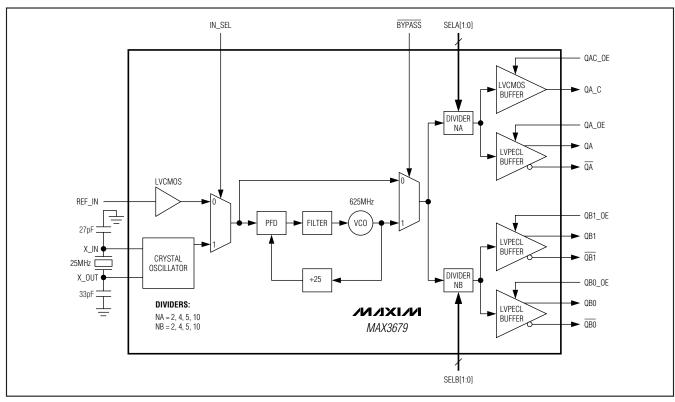
### TOP VIFW IN\_SEL X OUT ≅ × QBO REF 3BO QB1 0B1 32 31 30 29 28 27 26 25 24 GND Vcco\_b 1 GND 2 : 23 QB1\_OE 22 SELA1 QB0\_OE 3 SELA0 21 SELB1 /VI/IXI/VI MAX3679 SELB0 20 QA OE GND QAC OE 19 6 \*EP ¦ 18 MR 7 Vcc GNDO A 8 17 V<sub>CCA</sub> 9 10 11 12 13 14 15 16 8 BYPASS VDD0\_A VCCO A RES1 **RESO** g THIN QFN (5mm × 5mm) \*EXPOSED PAD CONNECTED TO GROUND.

### **Chip Information**

TRANSISTOR COUNT: 10,780 **PROCESS: BICMOS** 

Pin Configuration

### \_Block Diagram



### **Package Information**

\_\_\_\_ 11

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
32 TQFN-EP	T3255+3	<u>21-0140</u>

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